

Instruction

ECN CODE ▲

[1812022R] SERIESWafer Connector,Pitch 1.25mm
SMT,Type 2**Physical:****Housing:** High Temperature Thermoplastic**Contact:** Copper Alloy**Specifications:****Voltage Current Rating:** 3A max**Insulation Resistance:** 1000M ohm min**Contact Resistance:** 20m ohm max**Dielectric Withstanding Voltage:** 800VAC**Temperature Rating:** -25°C To +85°C**IR Reflow Soldering Temperature:**

Lead Part: 220°C,5sec

RoHS Part: 260°C,5sec

ORDERING CODE:**1812022 R 08 00 N46 -LF -R**
1 2 3 4 5 6 7

1.SERIES NO.

2.NO. OF STYLE

R=RIGHT ANGLE

3.NO. OF PINS

4.PLATED

00=TIN PLATED

5.HOUSING MATERIAL

N46=NY46

6.PRODUCT'S STATUS

NON-SHOWED=STANDARD TYPE

LF=RoHS COMPLIANT

► 7.PACKAGE

R=REEL

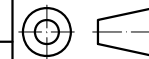
TOP VIEW
PCB LAYOUT RECOMMENDED

3 PINS

2 PINS

| | | | |
|-----|------------|-------------|------------|
| ③ | TERMINAL | BRASS T=0.3 | Sn-Plating |
| ② | HOUSING | NY46 | IVORY |
| ① | Ground Pad | BRASS | Sn-Plating |
| NO. | PART NAME | MATERIAL | STATUS |

| REV. | DATE | APPD. | CHR. | DR. | TOLERANCE UNLESS OTHERWISE SPECIFIED |
|------|------------|--------|--------|------|--------------------------------------|
| 1.0 | 2006/11/25 | DENNIS | DDP | LILY | 0.0±0.25 |
| 1.2 | 2012/06/21 | BING | DANIEL | MARK | 0.00±0.15 |
| 1.3 | 2012/06/28 | BING | DANIEL | MARK | ±3 |

ENGINEER
DWG

UNIT:mm

SIZE: A4

ANYTRONIC

CORPORATION LIMITED

TITLE WAFER CONNECTOR

DWG NO. 1812022RXXXXN46

SCALE 1:1 SHEET 1 OF 1